

Power line chokes

Current-compensated frame core double chokes 300 V AC, 0.7 ... 2.3 A, 10 ... 100 mH, +40 °C

Series/Type: B82733F/V

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Current-compensated frame core double chokes

Rated voltage 300 V AC Rated inductance 10 ... 100 mH Rated current 0.7 ... 2.3 A / +40 °C

Construction

- Current-compensated frame double chokes
- Closed magnetic circuit with frame construction made of ferrite
- Epoxy coating (UL94 V-0)
- Plastic coil former (UL94 V-0)
- 2-section winding
- Sector winding
- Clearance and creepage distances >4 mm

Features

- High inductance with low resistance
- Approx. 2% stray inductance for symmetrical interference suppression
- High pulse-handling capability
- Very good inductance/rated current ratio
- Low height (14 mm, B82733F)
- Suitable for wave soldering
- Design complies with EN 60938-2 (VDE 0565-2) and UL 1283
- ENEC (VDE) and UL approval **3 9 1**
- RoHS-compatible

Applications

- Suppression of common-mode and differential-mode interferences
- Electronic ballasts for lamps
- Switch-mode power applications

Terminals

- Base material CP wire
- Hot dipped
- Pins 0.7 × 0.7 mm
- Lead spacing:

B82733F: $20 \times 22.5 \text{ mm}$ B82733V: $10 \times 18.75 \text{ mm}$

Marking

Product brand, date of manufacture (YYWWD), production place identification code, ordering code, approval signs

Delivery mode

Blister tray (anti-static) in cardboard box





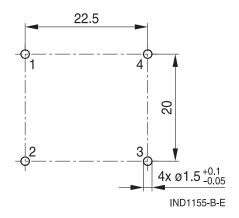


Current-compensated frame core double chokes

Dimensional drawing and layout recommendation

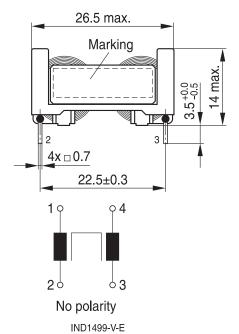
B82733F (horizontal version)

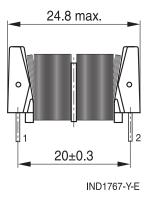
Recommended PCB layout (top view)



Tolerances to ISO 2768-cl / ISO 8015. Size ISO 14405 © All dimensions in mm

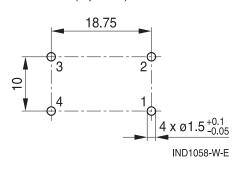
IND1245-O-E



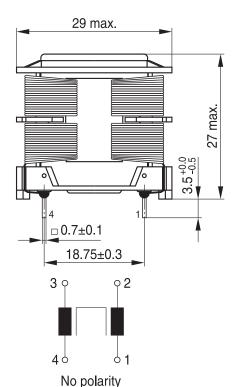


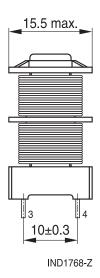
B82733V (vertical version)

Recommended PCB layout (top view)



Tolerances to ISO 2768-cl / ISO 8015. Size ISO 14405 (E) All dimensions in mm





IND1500-X-E



Current-compensated frame core double chokes

Technical data and measuring conditions

300 V AC (50/60 Hz)
2000 V AC, 2 s (line/line)
+40 °C
Referred to 50 Hz and rated temperature
Measured with Agilent 4284A at 10 kHz, 0.1 mA, +20 °C. Inductance is specified per winding.
-30/+50% at +20 °C
<10% at DC magnetic bias with I _R , +20 °C
Measured with Agilent 4284A at 10 kHz, 5 mA, +20 °C, typical values
Measured at +20 °C; typical values, specified per winding
Sn96.5Ag3.0Cu0.5: +(245 \pm 5) °C, (3 \pm 0.3) s Wetting of soldering area \geq 95% (to IEC 60068-2-20, test Ta)
+(260 ±5) °C, (10 ±1) s (to IEC 60068-2-20, test Tb)
40/125/56 (to IEC 60068-1)
P2 (to IEC 61558-1)
–25 °C +40 °C, ≤ 75% RH
Approx. 18 g
EN 60938-2, UL 1283



Current-compensated frame core double chokes

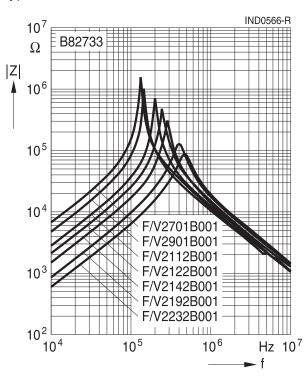
Characteristics and ordering codes

I_R	L _R	L _{stray,typ}	R _{typ}	Ordering code		Approva	als
Α	mH	μН	mΩ	horizontal	vertical	Ď ^V E	<i>9</i> 11
0.7	100	2100	1810	B82733F2701B001	B82733V2701B001	×	×
0.9	68	1440	1100	B82733F2901B001	B82733V2901B001	×	×
1.1	47	970	804	B82733F2112B001	B82733V2112B001	×	×
1.2	39	800	696	B82733F2122B001	B82733V2122B001	×	×
1.4	27	550	440	B82733F2142B001	B82733V2142B001	×	×
1.9	15	310	279	B82733F2192B001	B82733V2192B001	×	×
2.3	10	210	188	B82733F2232B001	B82733V2232B001	×	×

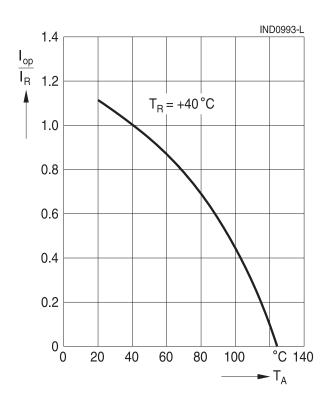
 $[\]times$ = approval granted

Impedance |Z| versus frequency f

measured with windings in parallel at +20 °C, typical values



Current derating I_{op}/I_R versus ambient temperature T_A





Cautions and warnings

- Please note the recommendations in our Inductors data book (latest edition) and in the data sheets.
 - Particular attention should be paid to the derating curves given there.
 - The soldering conditions should also be observed. Temperatures quoted in relation to wave soldering refer to the pin, not the housing.
- If the components are to be washed varnished it is necessary to check whether the washing varnish agent that is used has a negative effect on the wire insulation, any plastics that are used, or on glued joints. In particular, it is possible for washing varnish agent residues to have a negative effect in the long-term on wire insulation.

 Washing processes may damage the product due to the possible static or cyclic mechanical loads (e.g. ultrasonic cleaning). They may cause cracks to develop on the product and its parts, which might lead to reduced reliability or lifetime.
- The following points must be observed if the components are potted in customer applications:
 - Many potting materials shrink as they harden. They therefore exert a pressure on the plastic housing or core. This pressure can have a deleterious effect on electrical properties, and in extreme cases can damage the core or plastic housing mechanically.
 - It is necessary to check whether the potting material used attacks or destroys the wire, wire insulation, plastics or glue.
 - The effect of the potting material can change the high-frequency behaviour of the components.
 - Many coating materials have a negative effect (chemically and mechanically) on the winding wires, insulation materials and connecting points. Customers are always obligated to determine whether and to what extent their coating materials influence the component. Customers are responsible and bear all risk for the use of the coating material. TDK Electronics does not assume any liability for failures of our components that are caused by the coating material.
- Ceramics / Ferrites are sensitive to direct impact. This can cause the core material to flake, or lead to breakage of the core.
- Even for customer-specific products, conclusive validation of the component in the circuit can only be carried out by the customer.

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Important notes

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